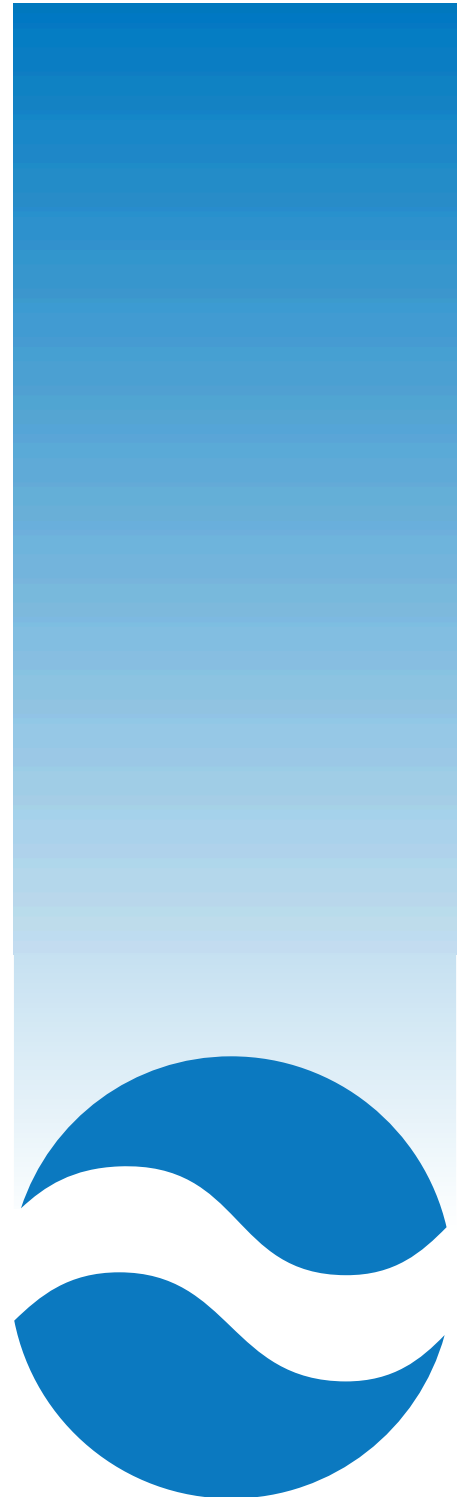


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***JOINT  
INDUSTRY  
STANDARD***

Handling, Packing,  
Shipping and  
Use of Moisture,  
Reflow, and Process  
Sensitive Devices



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The material in this joint standard was developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the IPC Plastic Chip Carrier Cracking Task Group (B-10a)

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IPC/JEDEC J-STD-033D



# Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices

A joint standard developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

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